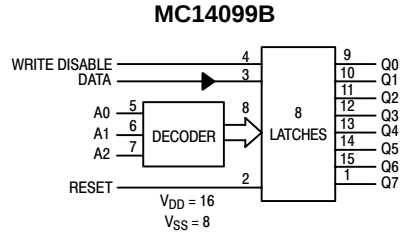
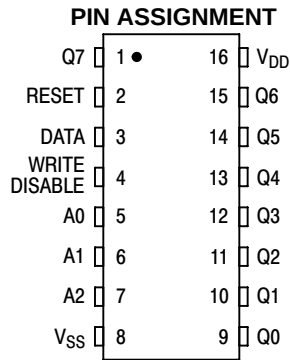


MC14099B



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14099BCP	PDIP-16	500 Units / Rail
MC14099BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14099BDW	SOIC-16 WB	47 Units / Rail
MC14099BDWG	SOIC-16 WB (Pb-Free)	47 Units / Rail
MC14099BDWR2	SOIC-16 WB	1000 Units / Tape & Reel
MC14099BDWR2G	SOIC-16 WB (Pb-Free)	1000 Units / Tape & Reel
MC14099BFEL	SOEIAJ-16	2000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	– 55° C		25° C			125° C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage V _{in} = V _{DD} or 0	“0” Level V _{OL}	5.0	–	0.05	–	0	0.05	–	0.05	Vdc
		10	–	0.05	–	0	0.05	–	0.05	
		15	–	0.05	–	0	0.05	–	0.05	
	“1” Level V _{OH}	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
		10	9.95	–	9.95	10	–	9.95	–	
		15	14.95	–	14.95	15	–	14.95	–	
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	“0” Level V _{IL}	5.0	–	1.5	–	2.25	1.5	–	1.5	Vdc
		10	–	3.0	–	4.50	3.0	–	3.0	
		15	–	4.0	–	6.75	4.0	–	4.0	
	“1” Level V _{IH}	5.0	3.5	–	3.5	2.75	–	3.5	–	Vdc
		10	7.0	–	7.0	5.50	–	7.0	–	
		15	11	–	11	8.25	–	11	–	
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source I _{OH}	5.0	– 3.0	–	– 2.4	– 4.2	–	– 1.7	–	mAdc
		5.0	– 0.64	–	– 0.51	– 0.88	–	– 0.36	–	
		10	– 1.6	–	– 1.3	– 2.25	–	– 0.9	–	
		15	– 4.2	–	– 3.4	– 8.8	–	– 2.4	–	
	Sink I _{OL}	5.0	0.64	–	0.51	0.88	–	0.36	–	mAdc
		10	1.6	–	1.3	2.25	–	0.9	–	
		15	4.2	–	3.4	8.8	–	2.4	–	
Input Current	I _{in}	15	–	± 0.1	–	± 0.00001	± 0.1	–	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	–	–	–	–	5.0	7.5	–	–	pF
Input Capacitance MC14599B — Data (pin 3) (V _{in} = 0)	C _{in}	–	–	–	–	15	22.5	–	–	pF
Quiescent Current (Per Package)	I _{DD}	5.0	–	5.0	–	0.005	5.0	–	150	μAdc
		10	–	10	–	0.010	10	–	300	
		15	–	20	–	0.015	20	–	600	
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15	I _T = (1.5 μA/kHz) f + I _{DD} I _T = (3.0 μA/kHz) f + I _{DD} I _T = (4.5 μA/kHz) f + I _{DD}							μAdc

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.004.

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SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

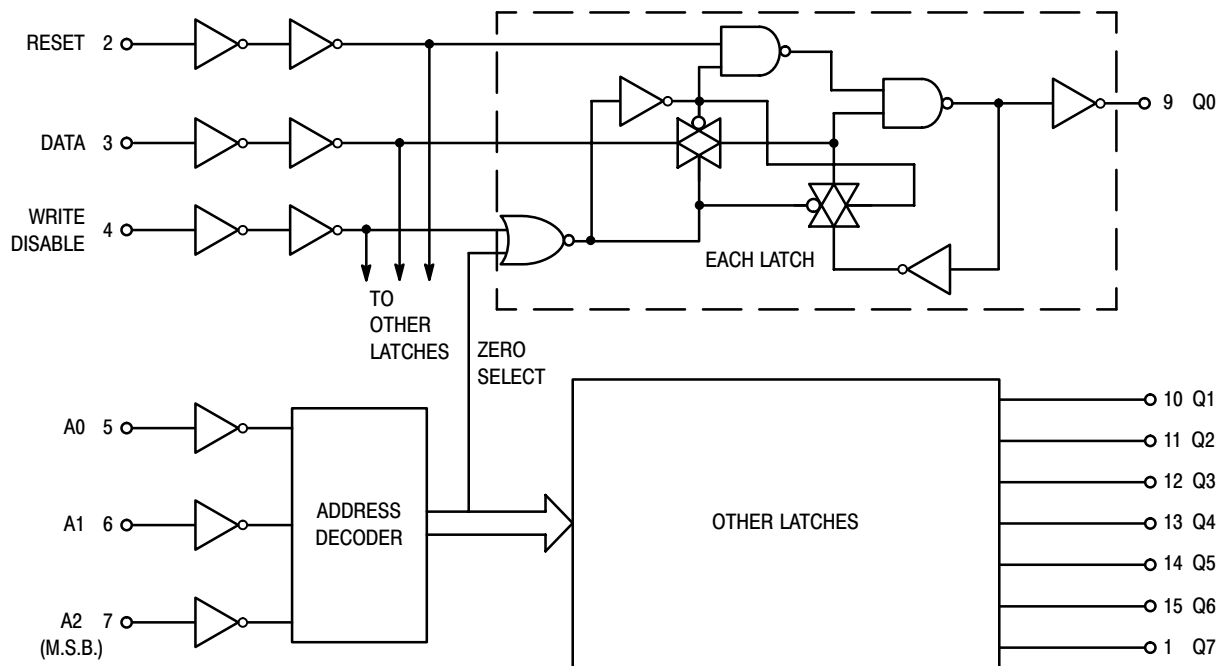
Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time t_{TLH} , $t_{THL} = (1.35 \text{ ns/pF}) C_L + 32 \text{ ns}$ t_{TLH} , $t_{THL} = (0.6 \text{ ns/pF}) C_L + 20 \text{ ns}$ t_{TLH} , $t_{THL} = (0.4 \text{ ns/pF}) C_L + 20 \text{ ns}$	t_{TLH} , t_{THL}	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Data to Output Q	t_{PHL} , t_{PLH}	5.0 10 15	– – –	200 75 50	400 150 100	ns
Write Disable to Output Q		5.0 10 15	– – –	200 80 60	400 160 120	ns
Reset to Output Q		5.0 10 15	– – –	175 80 65	350 160 130	ns
CE to Output Q (MC14599B only)		5.0 10 15	– – –	225 100 75	450 200 150	ns
Propagation Delay Time, MC14599B only Chip Enable, Write/Read to Data	t_{PHL} , t_{PLH}	5.0 10 15	– – –	200 80 65	400 160 130	ns
Address to Data		5.0 10 15	– – –	200 90 75	400 180 150	ns
Pulse Widths Reset	$t_{W(H)}$ $t_{W(L)}$	5.0 10 15	150 75 50	75 40 25	– – –	ns
Write Disable		5.0 10 15	320 160 120	160 80 60	– – –	ns
Set Up Time Data to Write Disable	t_{SU}	5.0 10 15	100 50 35	50 25 20	– – –	ns
Hold Time Write Disable to Data	t_H	5.0 10 15	150 75 50	75 40 25	– – –	ns
Set Up Time Address to Write Disable	t_{SU}	5.0 10 15	100 80 40	45 30 10	– – –	ns
Removal Time Write Disable to Address	t_{REM}	5.0 10 15	0 0 0	– 80 – 40 – 40	– – –	ns

5. The formulas given are for the typical characteristics only at 25°C .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

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FUNCTION DIAGRAM



TRUTH TABLE

Write Disable	Reset	Addressed Latch	Unaddressed Latches
0	0	Data	Q_n^*
0	1	Data	Reset [†]
1	0	Q_n^*	Q_n^*
1	1	Reset	Reset

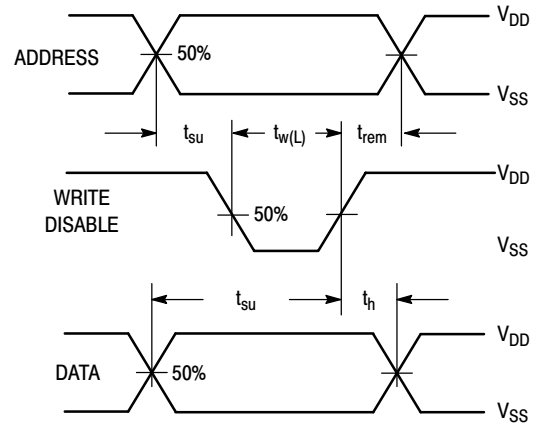
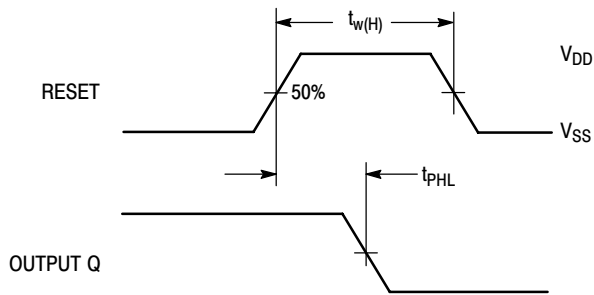
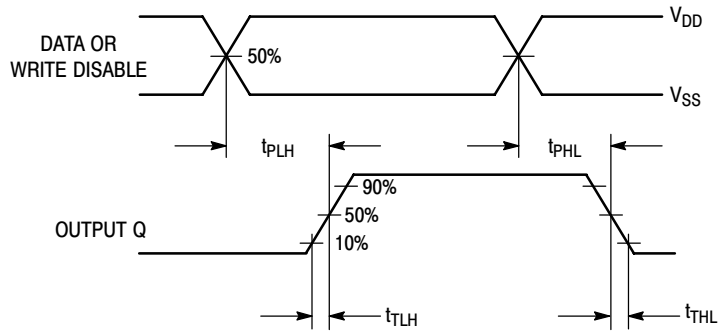
* Q_n is previous state of latch.

[†]Reset to zero state.

CAUTION: To avoid unintentional data changes in the latches, Write Disable must be active (high) during transitions on the address inputs A0, A1, and A2.

MC14099B

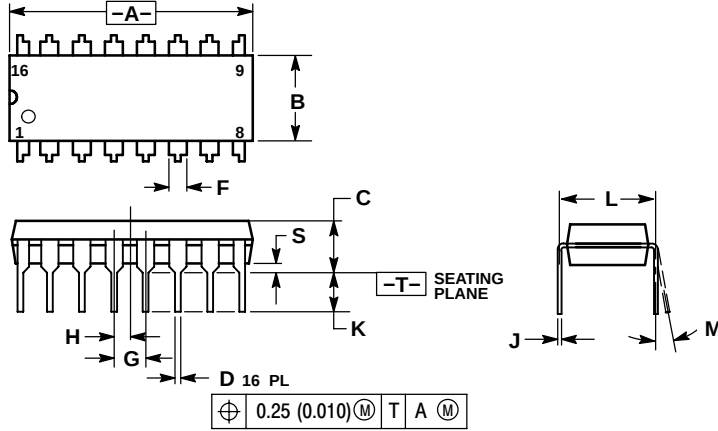
SWITCHING WAVEFORMS



MC14099B

PACKAGE DIMENSIONS

PDIP-16
P SUFFIX
 PLASTIC DIP PACKAGE
 CASE 648-08
 ISSUE T

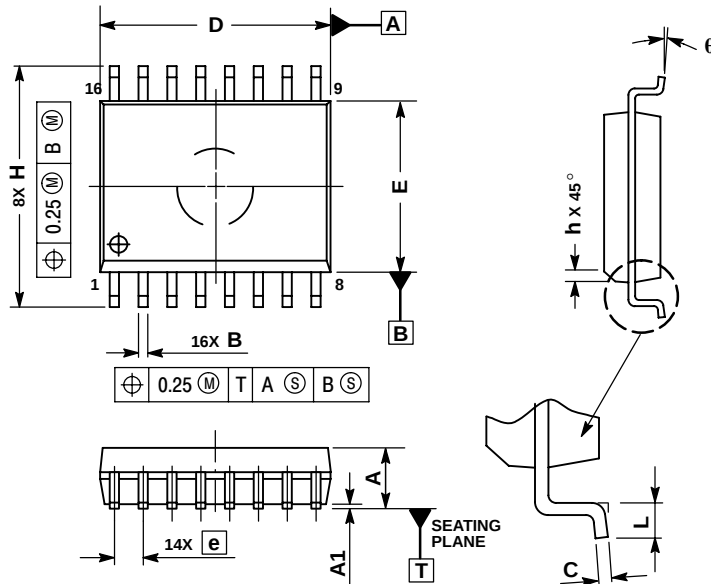


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOIC-16 WB
DW SUFFIX
 PLASTIC SOIC PACKAGE
 CASE 751G-03
 ISSUE C



NOTES:

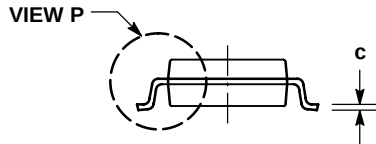
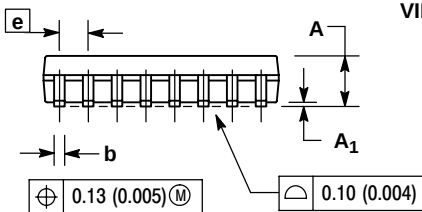
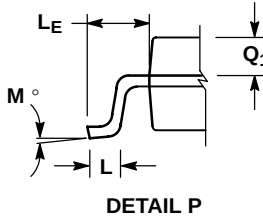
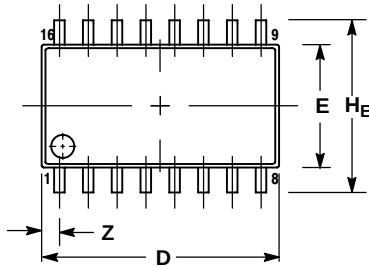
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27	BSC
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
q	0°	7°

MC14099B

PACKAGE DIMENSIONS

SOEIAJ-16 F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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